

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Title of Invention

ENCAPSULATED PIN STRUCTURE FOR IMPROVED
RELIABILITY OF WAFER

Application Number :

Confirmation Number:

First Named Applicant: Tien-Jen Cheng

Attorney Docket Number: FIS920030103US1

Art Unit:

Examiner:

Search string: (5773889 or 5989935 or 6300236 or 6449840 or 6500324 or 20020179689).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

| init | Cite.No. | Patent No. | Date | Patentee | Kind | Class | Subclass |
|-----------|----------|------------|------------|--------------------|------|-------|----------|
| <i>MP</i> | 1 | 5773889 | 1998-06-30 | LOVE, ET AL. | | | |
| <i>N</i> | 2 | 5989935 | 1999-11-23 | ABBOTT | | | |
| <i>AS</i> | 3 | 6300236 | 2001-10-09 | HARPER, ET AL. | | | |
| <i>N</i> | 4 | 6449840 | 2002-09-17 | LE, ET AL. | | | |
| <i>AS</i> | 5 | 6500324 | 2002-12-31 | SIMPSON, ET AL. | | | |

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

| init | Cite.No. | Pub. No. | Date | Applicant | Kind | Class | Subclass |
|-----------|----------|-------------|------------|-----------|------|-------|----------|
| <i>AS</i> | 1 | 20020179689 | 2002-12-05 | TUNG | | | |

Signature

| Examiner Name | Date |
|-------------------------------|---------|
| <i>William C. [Signature]</i> | 4/13/06 |